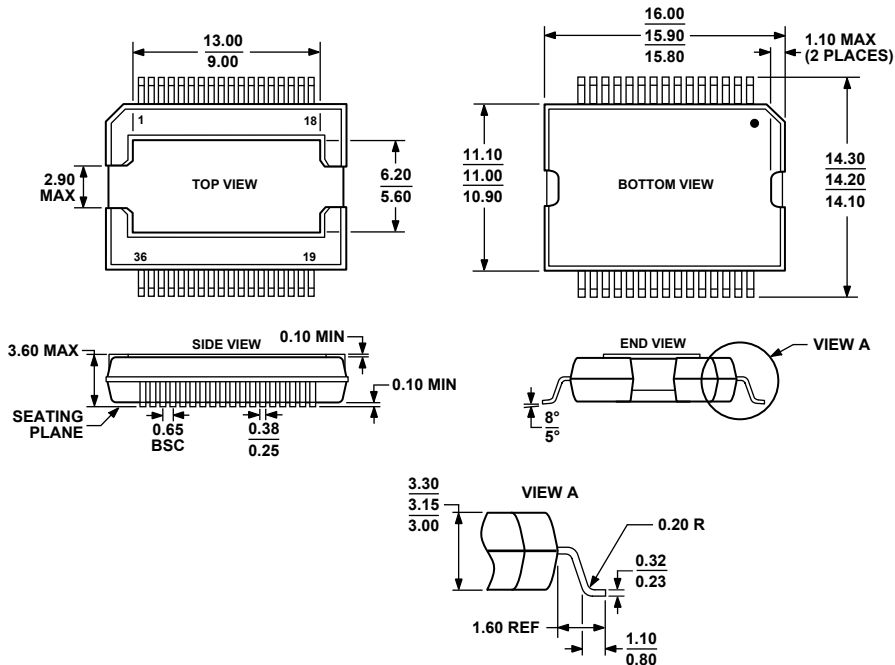


36-Lead Power SOIC, Thermally Enhanced Package [PSOP_3]

(RR-36-2)

Dimensions shown in millimeters



COMPLIANT TO JEDEC STANDARDS MO-166-AE
WITH THE EXCEPTION TO PAD ORIENTATION.